

This listing of claims replaces all prior versions and listings of claims in the application:

Listing of Claims:

1. (Currently Amended) A communication module comprising:  
a semiconductor member;  
a flexible printed circuit board on which said semiconductor member is mounted and to which said semiconductor member is electrically connected;  
a stem through which said board is inserted and to which said board is ~~then~~ fixed,  
wherein said board comprises polyimide resin and is fixed to the stem with a fixing material having a melting point in a range of 300 to 350 °C; and  
a cap so disposed as to cover said semiconductor member.
2. (Original) The communication module according to claim 1, wherein the semiconductor member is at least one of a light emitting element, a light receiving element and an integrated circuit.
3. (Previously Presented) The communication module according to claim 1, wherein the flexible printed circuit board includes a type of lines selected from among coplanar lines, micro-strip lines, and grounded coplanar lines.
4. (Previously Presented) The communication module according to claim 1, wherein a plurality of different flexible printed circuit boards are fixed to the stem.

5. (Currently Amended) The communication module according to claim 1, wherein an end of the flexible printed circuit board(s) that protrudes from the stem has a connector that can connect to a subsequent-stage circuit board.

6. (Currently Amended) The communication module according to claim 1, wherein the flexible printed circuit board(s) exhibits a bent-shape when in a plane.